

PECVD (SiNx)

Designed to apply anti-reflective coating to the surface of crystalline silicon wafers to reduce reflection for greater efficiency.

SOLAR TECHNOLOGY CELL PROCESS MACHINE

Technical Specification

Format(mm)	5,490(W) x 8,490(L) x 4,265(H)
Weight(kg)	10,800 * 2
Gas Supply	SiH4, NH3, N2O
Number of Chamber	10
Cycle Time(min)	36
Uptime(%)	97
Boat Capacity	468 wafers/Boat
Wafer Throughput	7,600 wafers with boat wafer 468
Cell Type	Monocrystalline, Multicrystalline Silicon wafers
Cell Size(mm)	M2(156*156) ~ M10(185*185)
Cell Thickness(um)	120 ~ 200(±20)
Process Temperature(°C)	200 ~ 550
Process Pressure(Torr)	0.5 ~ 3.0

Dimension

